

MOS FIELD EFFECT TRANSISTOR 2SJ603

SWITCHING P-CHANNEL POWER MOS FET

DESCRIPTION

The 2SJ603 is P-channel MOS Field Effect Transistor designed for solenoid, motor and lamp driver.

FEATURES

- Super low on-state resistance:
 - $R_{DS(on)1} = 48 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = -10 \text{ V, I}_D = -13 \text{ A)}$
- RDS(on)2 = 75 m Ω MAX. (VGS = -4.0 V, ID = -13 A)
- Low input capacitance:
 - $C_{iss} = 1900 \text{ pF TYP.} (V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V})$
- Built-in gate protection diode

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SJ603	TO-220AB
2SJ603-S	TO-262
2SJ603-ZJ	TO-263
2SJ603-Z	TO-220SMD Note

Note TO-220SMD package is produced only in Japan.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	-60	V
Gate to Source Voltage (Vps = 0 V)	Vgss	∓ 2 0	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	∓25	Α
Drain Current (pulse) Note1	ID(pulse)	∓70	Α
Total Power Dissipation (Tc = 25°C)	Рт	50	W
Total Power Dissipation (T _A = 25°C)	PT	1.5	W
Channel Temperature	T_ch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	-25	Α
Single Avalanche Energy Note2	Eas	62.5	mJ

Notes 1. PW \leq 10 μ s, Duty cycle \leq 1%

2. Starting Tch = 25°C, VdD = -30 V, Rg = 25 Ω , Vgs = -20 \rightarrow 0 V

(TO-220AB)



(TO-262)



(TO-263, TO-220SMD)



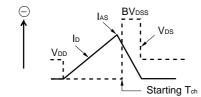
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ELECTRICAL CHARACTERISTICS (TA = 25°C)

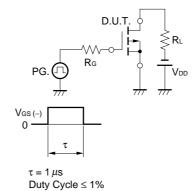
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ipss	V _{DS} = -60 V, V _{GS} = 0 V			-10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \mp 20 \text{ V}, V_{DS} = 0 \text{ V}$			∓10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-1.5	-2.0	-2.5	V
Forward Transfer Admittance	y fs	V _{DS} = -10 V, I _D = -13 A	10	21		S
Drain to Source On-state Resistance	RDS(on)1	Ves = -10 V, ID = -13 A		38	48	mΩ
	R _{DS(on)2}	$V_{GS} = -4.0 \text{ V}, I_{D} = -13 \text{ A}$		53	75	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V		1900		pF
Output Capacitance	Coss	Vgs = 0 V		350		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		140		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = -30 V, I _D = -13 A		10		ns
Rise Time	tr	Vgs = -10 V		11		ns
Turn-off Delay Time	t _{d(off)}	$R_G = 0 \Omega$		66		ns
Fall Time	tf	4.47	_	20		ns
Total Gate Charge	QG	V _{DD} = -48 V	U	38		nC
Gate to Source Charge	Qgs	Vgs = -10 V		7		nC
Gate to Drain Charge	Q _{GD}	$R_{G} = 0 \Omega$ $V_{DD} = -48 \text{ V}$ $V_{GS} = -10 \text{ V}$ $I_{D} = -25 \text{ A}$		10		nC
Body Diode Forward Voltage	VF(S-D)	IF = 25 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 25 A, VGS = 0 V		49		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ μs		100		nC

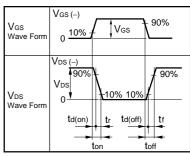
TEST CIRCUIT 1 AVALANCHE CAPABILITY

$R_{G} = 25 \Omega$ $PG. \qquad \qquad \downarrow V$ V_{DD} V_{DD}

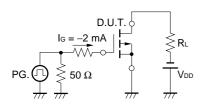


TEST CIRCUIT 2 SWITCHING TIME

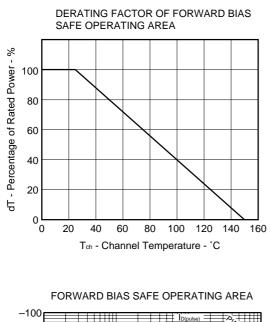


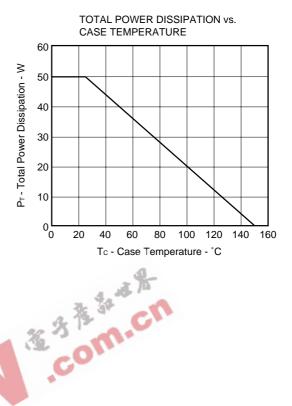


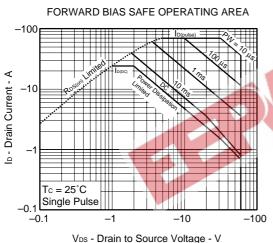
TEST CIRCUIT 3 GATE CHARGE

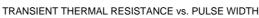


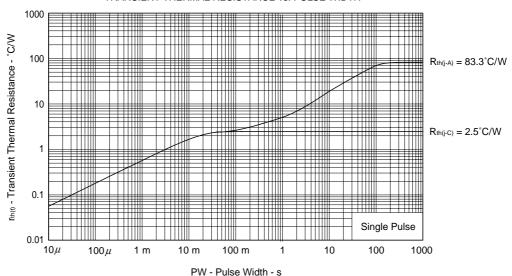
TYPICAL CHARACTERISTICS (TA = 25°C)





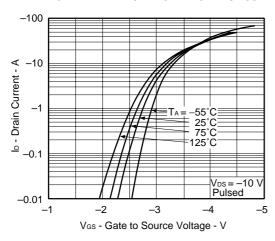




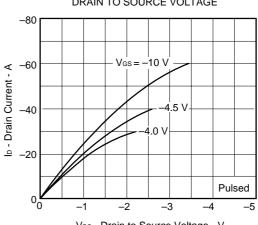


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FORWARD TRANSFER CHARACTERISTICS

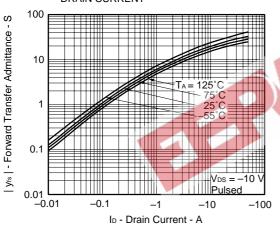


DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

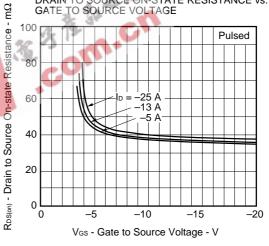


V_{DS} - Drain to Source Voltage - V

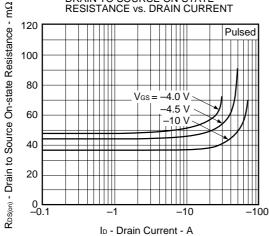




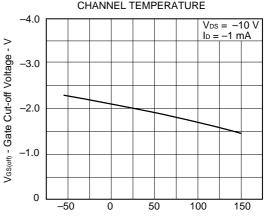
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



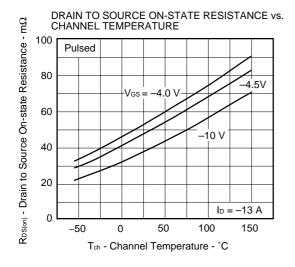
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

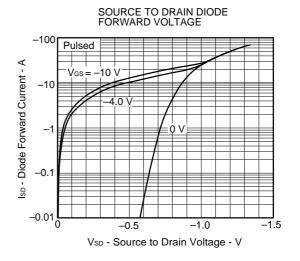


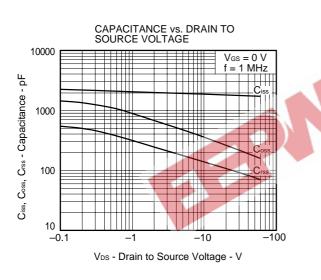
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

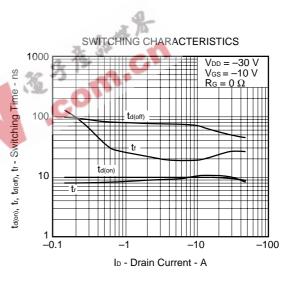


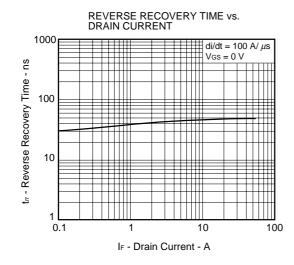
 T_{ch} - Channel Temperature - $^{\circ}C$

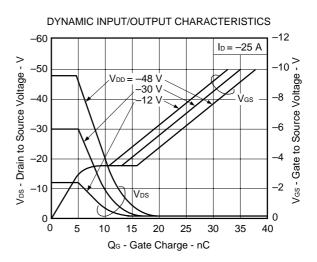


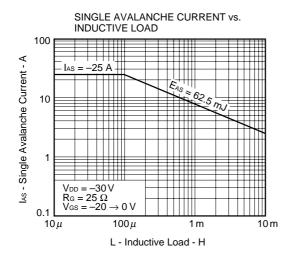


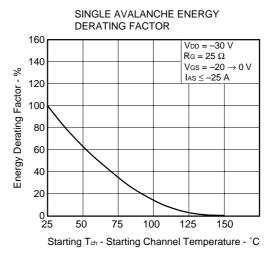






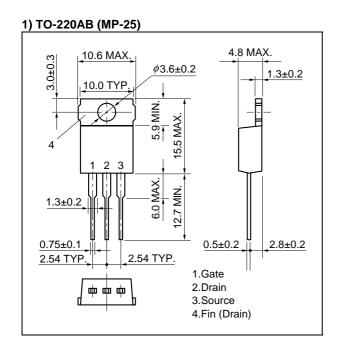


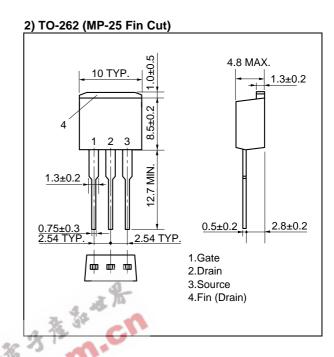


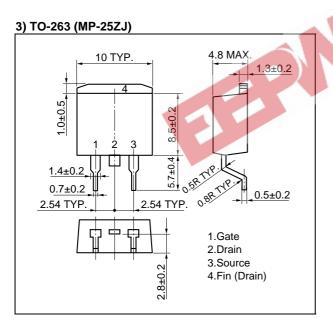


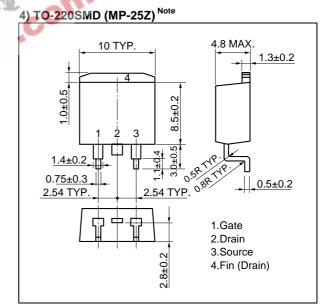


★ PACKAGE DRAWINGS (Unit: mm)



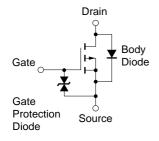






Note This package is produced only in Japan.

EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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